



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSO200P03S H	Issued	12. August 2021
MA#	MA005617652		
Package	PG-DSO-8-39	Weight*	83.58 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.664	1.99	1.99	19905	19905
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		123	
	non noble metal	zinc	7440-66-6	0.041	0.05		490	
	non noble metal	iron	7439-89-6	0.820	0.98		9805	
	non noble metal	copper	7440-50-8	33.276	39.81	40.85	398139	408557
wire	non noble metal	copper	7440-50-8	0.139	0.17	0.17	1659	1659
encapsulation	organic material	carbon black	1333-86-4	0.231	0.28		2763	
	plastics	epoxy resin	-	7.160	8.57		85666	
	inorganic material	silicondioxide	60676-86-0	38.802	46.42	55.27	464254	552683
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9737	9737
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	868	868
glue	plastics	epoxy resin	-	0.083	0.10		989	
	noble metal	silver	7440-22-4	0.468	0.56	0.66	5602	6591
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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